APPLICATION DATA SHEET

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Title of Invention

[HIGH DENSITY SEMICONDUCTOR PACKAGE]

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Inventor Information:

Inventor 1:

Applicant Authority Type: Inventor Citizenship: TW

Name prefix: Mr.

Given Name: Sung-Fei Family Name: Wang

Residence:

City of Residence: Kaohsiung

Country of Residence: TW

Address-1 of Mailing Address: 1F., No. 21, Alley 90, Lane 729, Chia-Chang,

Address-2 of Mailing Address: Nan-Tzu District

City of Mailing Address: Kaohsiung

State of Mailing Address:

Postal Code of Mailing Address:

Country of Mailing Address: TW

Phone: Fax: E-mail:

Attorney Information:

practitioner(s) at Customer Number:

31561



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